SPOTTER-VT

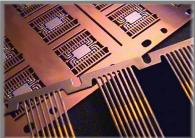


The **SPOTTER-VT** unit is of the same family that the SPOTTER-HS but it combines two interlocked endless flexible masking belts which travel, *in vertical position*, around two compact jet plating cells.

This linear cell system enable soluble or insoluble anode plating processes to operate at extremely high plating rates, whilst producing close tolerances and excellent thickness distribution from component to component.

The outstanding accuracy, with each spot accurate to less than +/- 0.1 mm, combined with the masking forms of the silicone molded inserts, is the guarantee of **substantial** saving of precious metal compare to conventional selective plating techniques.









The **SPOTTER-VT** allows the plating on flat semi-conductor frames or formed contact terminals with possibilities such as spot or stripe plating on one or **simultaneously** on two sides, precise and exclusive East/West plating of **contact edges** or North/South plating by inserting silicone masking forms between the contact terminals.



ELECTROPLATING ENGINEERING for SELECTIVE APPLICATIONS

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